

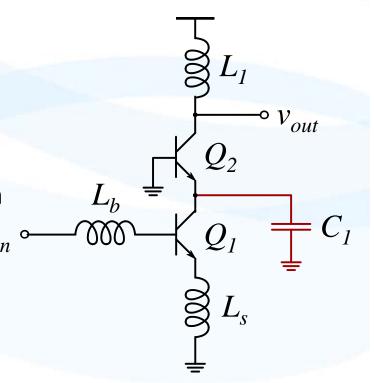




Departement Elektriese, Elektroniese & Rekenaar-Ingenieurswese Department of Electrical, Electronic & Computer Engineering Kgoro ya Merero ya Mohlagase, Elektroniki & Bointšinere bja Khomphutha

Introduction (1)

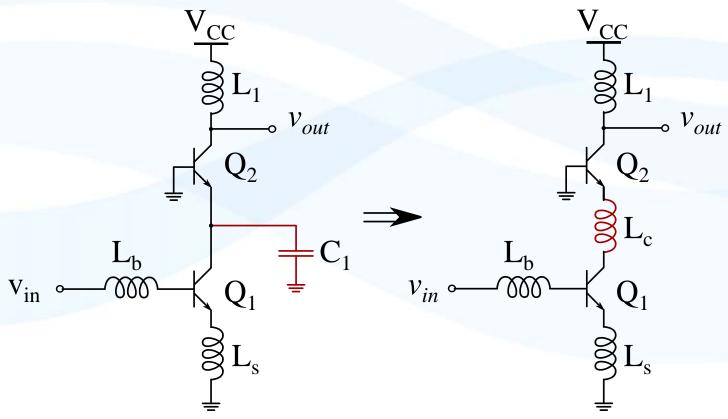
- Substrate losses particularly problematic at mm-Wave frequencies
 - Substrate conductivity
 - High frequency capacitive effects
- Performance of the cascode configuration vanishes at high frequency v_{in}
 - Shunts the AC current to ground
 - Reduces gain
 - Output stage increases noise





Introduction (2)

• A possible solution:



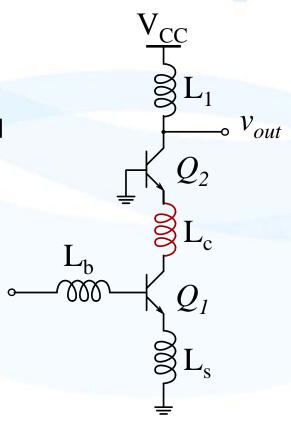


Introduction (3)

Research problem formulation:

Negative impact of poor inductor performance

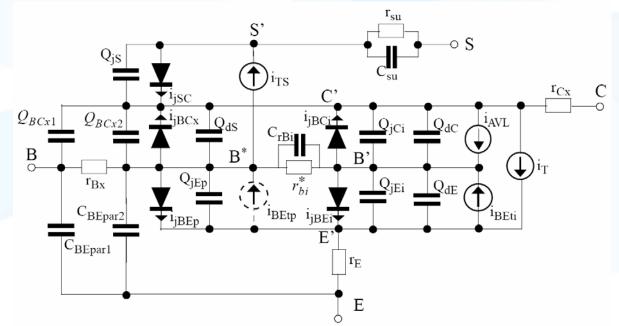
- Inductors L_b and L_s are part of a narrowband matching network
 - Low Q degrades noise figure
 - Noise figure degraded by 10 % [1]
- Inductor L_c fails to cancel the parasitic capacitance





Substrate effects (1)

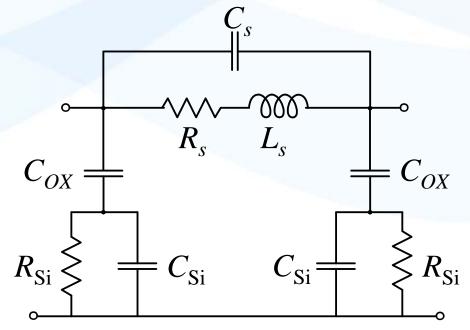
- HICUM
 - Substrate effects in transistors
 - Modelled as a simple RC network





Substrate effects (2)

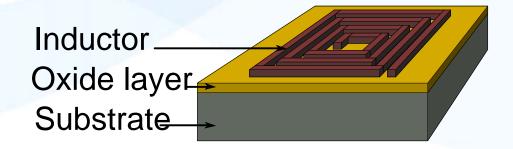
- Inductors
 - Also modelled as a RC network
 - Substrate coupling reduces the Q-factor and f_{sr}
 - Electric field penetrates the substrate causing severe energy loss





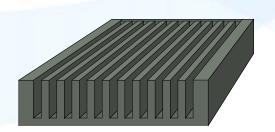
Inductors for mm-Wave applications (1)

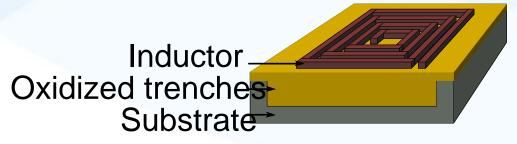
- Spiral inductors / transmission lines
 - On the Silicon substrate
 - Substrate losses becomes severe
 - Degrades Q and f_{sr}
 - Several techniques to improve inductor performance



Inductors for mm-Wave applications (2)

- MEMS technology
- Substrate trenches / bulk micromachining
 - Create thick trenches in the Silicon substrate
 - Oxidation process creates a thick oxide layer
 - Improves inductor substrate isolation
 - Improves Q and f_{sr}

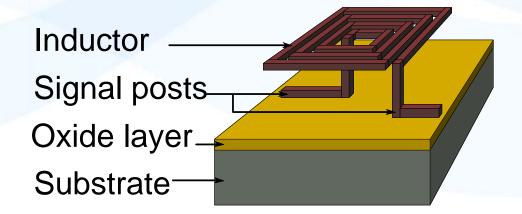






Inductors for mm-Wave applications (3)

- MEMS technology
 - Fabrication further away from the substrate
 - Tuneable
 - Structural support
 - Applications in the RF range



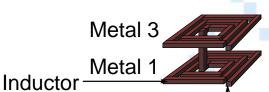


Inductors for mm-Wave applications (4)

- Metal layers
 - Inductor footprint is minimized by reducing the diameter and line-width
 - Fabricate using the metal layers to further Oxide layer reduce substrate coupling
 - Stacked inductors further reduce footprint area
 - Ground plane beneath the inductor simplifies inductor

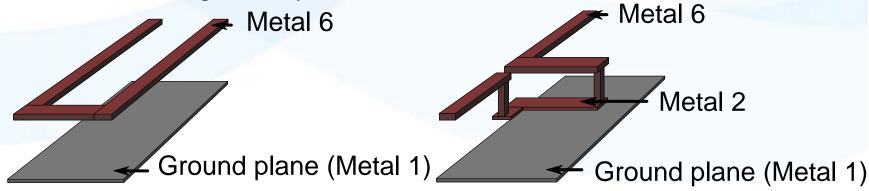
moda lictance		Area	Q	#Metal layer(s)	Туре
[2]	140 pH	29 μm × 29 μm	>20 above 40 GHz	9	Planar
[3]	420 pH	30 μm × 30 μm	13 @ 40 GHz	5,6	Stacked
[3]	420 pH	21 µm × 21 µm	>15 above 50 GHz	4,5,6	Stacked
[4]	380 pH	26 µm × 26 µm	11 @ 40 GHz	5,6 with ground plane	Stacked





Inductors for mm-Wave applications (5)

- Transmission lines can also provide an equivalent on-chip inductance
- Prominent advantage is using a ground plane
- Line length can be prohibitively long
 - Folded transmission line geometry
 - Series-stub geometry



Conclusion

- LNA performance is sensitive to inductor performance
- HICUM is able to accurately determine transistor losses
- Substrate losses reduces the Q and f_{sr} of the inductor
- Various techniques and methods exists to increase inductor performance
- Preferred inductor solution whether spiral inductors or transmission lines

References

- [1] S.P. Voinigescu *et al.*, "A Scalable High-Frequency Noise Model for Bipolar Transistors with Application to Optimal Transistor Sizing for Low-Noise Amplifier Design", *IEEE Journal of Solid-State Circuits*, vol. 32, no. 9, pp.1430-1439, September 1997.
- [2] T. Yao et al., "Algorithmic Design of CMOS LNAs and Pas for 60-GHz Radio", *IEEE Journal of Solid-State Circuits*, vol. 42, no. 5, pp. 1044-1057, May 2007.
- [3] T.O. Dickson *et al.*, "30-100-GHz Inductors and Transformers for Millimeter-Wave (Bi)CMOS Integrated Circuits", *IEEE Trans. on Microw. Theory Tech.*, vol. 53, no. 1, pp. 123-133, January 2005.
- [4] M.Q. Gordon, T. Yao and S.P. Voinigescu, "65-GHz Receiver in SiGe BiCMOS Using Monolithic Inductors and Transformers", *Digest:* Silicon Monolithic Integrated Circuits in RF Syst., San Diego, pp.265-268, 18-20 January 2006.

Feedback/Questions

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